L Number	Hits	Search Text	DB	Time stamp
1	5	device and mounting near substrate and	USPAT;	2004/06/11
		pressing and mounting adj pads and	US-PGPUB;	11:03
		project\$3 near electrodes	EPO; JPO;	
Į			DERWENT;	
			IBM_TDB	
2	20	Murakami near Tomoo .inv.	USPAT;	2004/06/11
			US-PGPUB;	11:03
ļ			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	0	device and substrate and mounting and	USPAT;	2004/06/11
	•	pressing and deforming and sealling and	US-PGPUB;	10:57
		29/\$.ccls.	1	10.57
		25/4.CCI3.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	644	device and substrate and mounting and	USPAT;	2004/06/11
		pressing and 29/\$.ccls.	US-PGPUB;	10:57
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
.	4	device and substrate and mounting and	USPAT;	2004/06/11
1		pressing and 29/\$.ccls. and mounting adj	US-PGPUB;	10:59
1		pads and project\$3 near electrodes	EPO; JPO;	
3			DERWENT;	
			IBM_TDB	
	4	device and substrate and mounting and	USPAT;	2004/06/11
	•	pressing and (74/260, 174/256 , 174/261 ,	US-PGPUB;	11:01
		257/E21.503 , 257/E21.511	1	11.01
		· ·	EPO; JPO;	
		, 257/E23.021 , 29/831 , 29/832 ,	DERWENT;	
		29/840).ccls. and mounting adj pads and	IBM_TDB	
		project\$3 near electrodes		
•	4	device and substrate and mounting and	USPAT;	2004/06/11
į		pressing and (29/830; 29/832 ; 29/836 ;	US-PGPUB;	11:01
1		29/840 ; 29/739 ; 29/841 ; 29/838	EPO; JPO;	
		; 29/839 ; 29/837 ; 228/180.22 ;	DERWENT;	
		257/772 ; 257/773 ; 257/775	IBM_TDB	
		; 257/737 ; 257/778 ; 361/768 ;		
		361/773 ; 361/774 ; 174/260		
•).ccls. and mounting adj pads and project\$3		
		near electrodes	1	

	Title	Current OR
1	Image recording material and lithographic printing plate precursor	430/270.1
2	Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance	438/108
3	Method of mounting a semiconductor device to a substrate and a mounted structure	29/840
4	METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE	174/260
5	Mounting method and apparatus of bare chips	438/113
6	Semiconductor device and semiconductor device mounting method thereof	257/684
7	Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance	438/108

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	Current XRef
1	430/302
2	257/E21.503; 257/E21.508
3	174/250; 174/260; 174/263; 257/E21.503; 257/E21.511; 257/E23.021; 29/854
4	174/256; 174/261; 257/E21.503; 257/E21.511; 257/E23.021; 29/831; 29/832; 29/840
5	257/E21.503; 257/E21.508; 257/E21.514
6	257/737; 257/E21.503; 438/612; 438/615
7	228/180.22; 257/778; 257/E21.503; 257/E21.508; 438/127; 438/666

	Title	Current OR
8	Method of mounting a semiconductor device to a substrate	29/840
9	Flip chip mounting method and apparatus therefor	29/840
10	Semiconductor element mounting method	438/108
11	Method for producing a semiconductor device	438/108

	Title	Current OR
12	Method for manufacturing wiring pattern board	427/96
13	Method of mounting a semiconductor device to a substrate and a mounted structure	257/775
14	Method for manufacturing a printed circuit board having electrodes on end surface of substrate	:
15	Method for manufacturing printed circuit board with through-hole	29/852
16	Method of and apparatus for plating printed circuit board	427/98

	Title	Current OR
17	Fabrication method of printed wiring board	427/510
18	Silver halide photographic material containing a silica containing overlayer and specific hydrazine derivatives	430/264
19	CONNECTION STRUCTURE BETWEEN PRINTED BOARDS	
20	Image recording material and lithographic printing plate precursor	

	Title	Current OR
1	Method of mounting a semiconductor device to a substrate and a mounted structure	29/840
2	METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE	174/260
3	Method of mounting a semiconductor device to a substrate	29/840

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Current XRef 174/250; 174/260; 174/263; 1 257/E21.503; 257/E23.021; 29/854 174/256; 174/261; 257/E21.503; 257/E21.511; 2 57/E23.021; 29/831; 29/832; 29/840 174/260; 257/778; 257/772; 257/775; 257/775; 257/775; 257/778; 257/E21.503; 257/E21.511; 3 257/E23.021; 29/832;		T
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